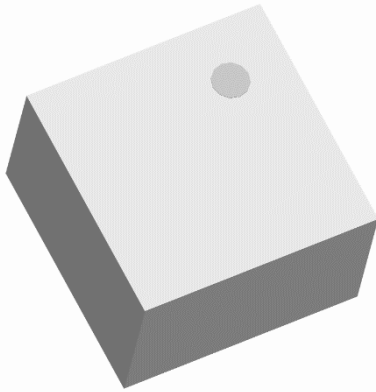




Ultra Low Profile Halogen Free 0404 Balun
50Ω to 100Ω Balanced

Description:



The BD0810N50100AHF is one of the world's smallest and highest performance, halogen free, low profile sub-miniature unbalanced to balanced transformer targeted at the 900MHz ISM bands as well as the low band WCDMA / GSM markets and designed specifically for differential inputs and output locations on modern chipsets in an easy to use surface mount package. The BD0810N50100AHF is ideal for high volume manufacturing and delivers higher performance than traditional ceramic baluns. The BD0810N50100AHF has an unbalanced port impedance of 50Ω and 100Ω balanced port impedance. The balanced ports have equal amplitude (-3dB) with 180 degree phase differential. The BD0810N50100AHF is available on tape and reel for pick and place high volume manufacturing.

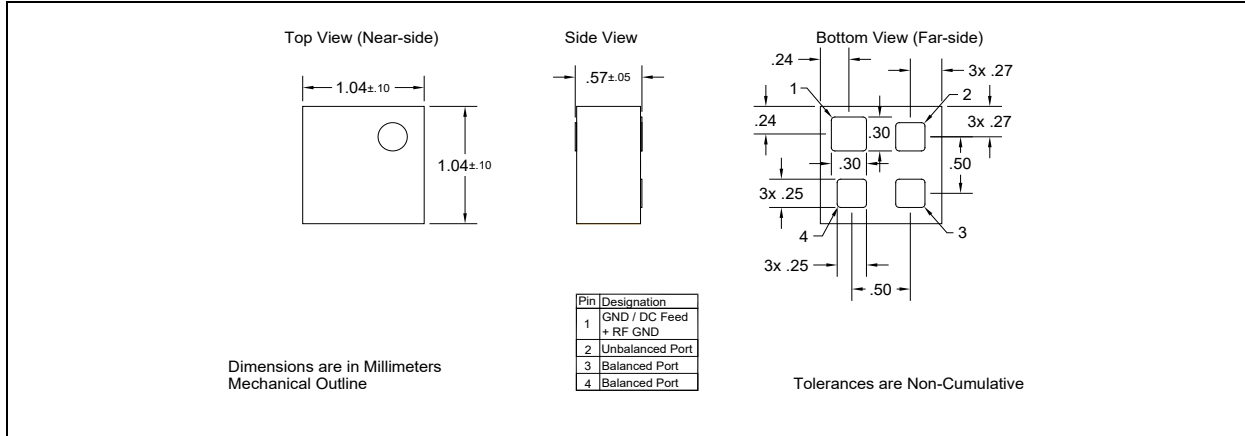
IMPORTANT: This balun must be used with a capacitor across the differential ports as shown on Page 4 to optimize the performance.

Detailed Electrical Specifications: Specifications subject to change without notice.

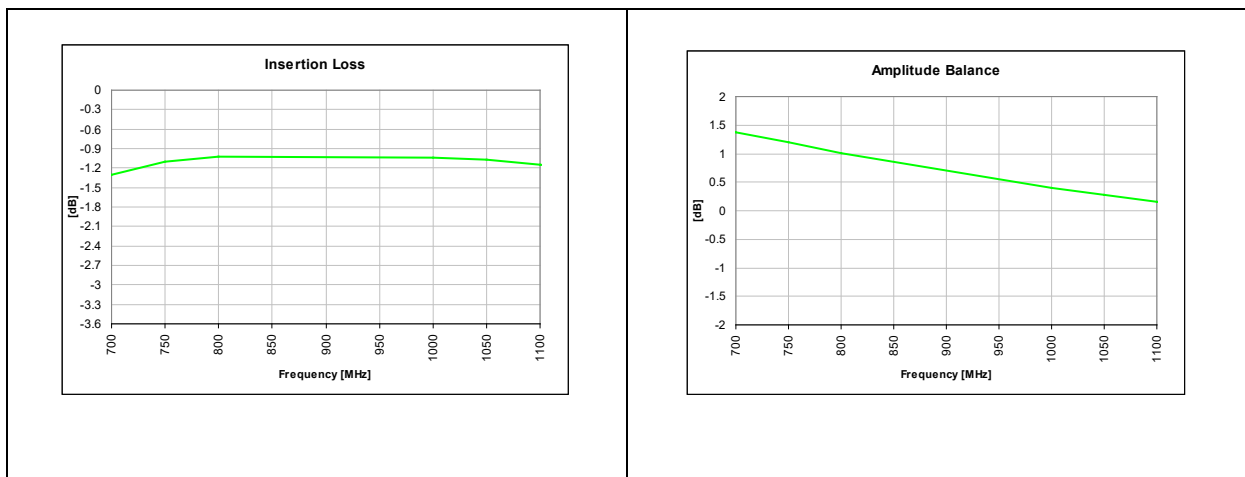
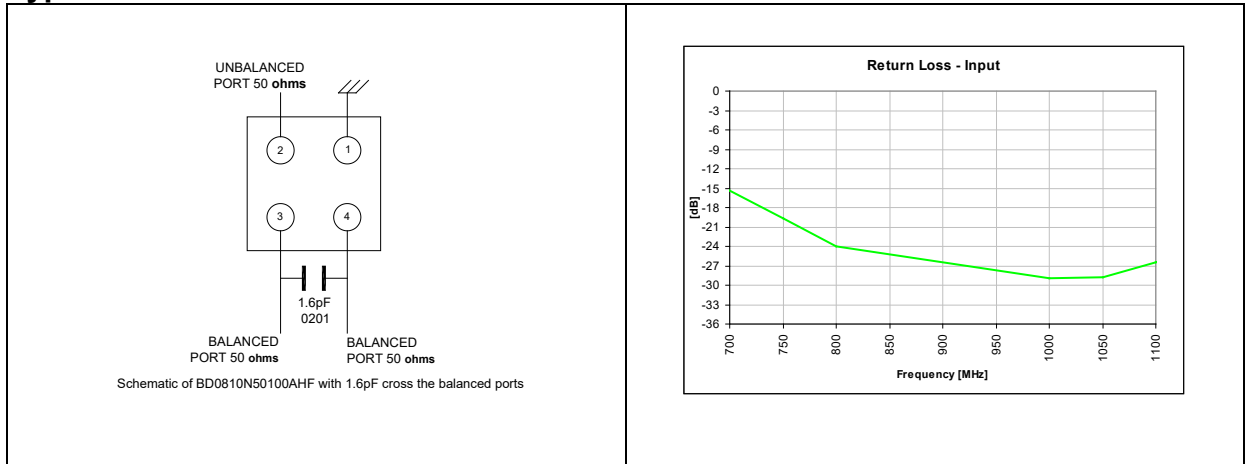
Features: 800 – 1000 MHz 0.57 mm Height Profile 50 Ohm to 2 x 50 Ohm Low Insertion Loss Class leading CMRR Targeted for WCDMA, GSM, PMR, ULPR & All ISM Protocols Surface Mountable Tape & Reel Non-conductive Top Surface RoHS Compliant Halogen Free	Parameter	ROOM (25°C)			Unit
		Min.	Typ.	Max	
	Frequency	800		1000	MHz
	Unbalanced Port Impedance		50		Ω
	Balanced Port Impedance		100		Ω
	Return Loss	18	24		dB
	Insertion Loss*		1.0	1.2	dB
	Amplitude Balance		1.0	1.4	dB
	Phase Balance		5	9	Degrees
	CMRR		24		dB
	Power Handling @85C			0.75	Watts
	Power Handling @105C			0.45	Watts
	Operating Temperature	-55		+105	°C

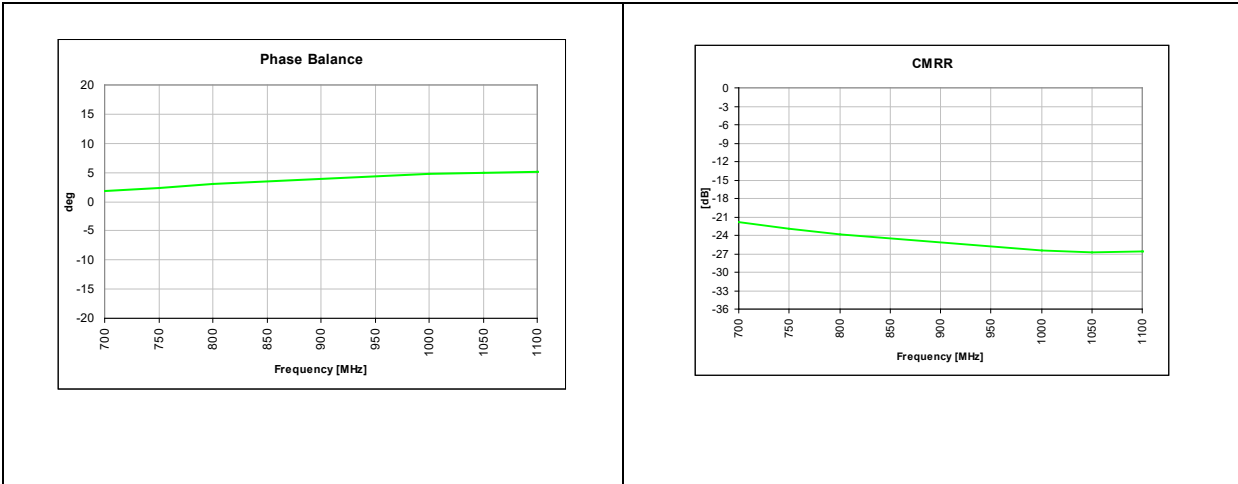
* Insertion Loss stated at room temperature. Values above are for the case with shunt capacitor across differential lines.

Outline Drawing:

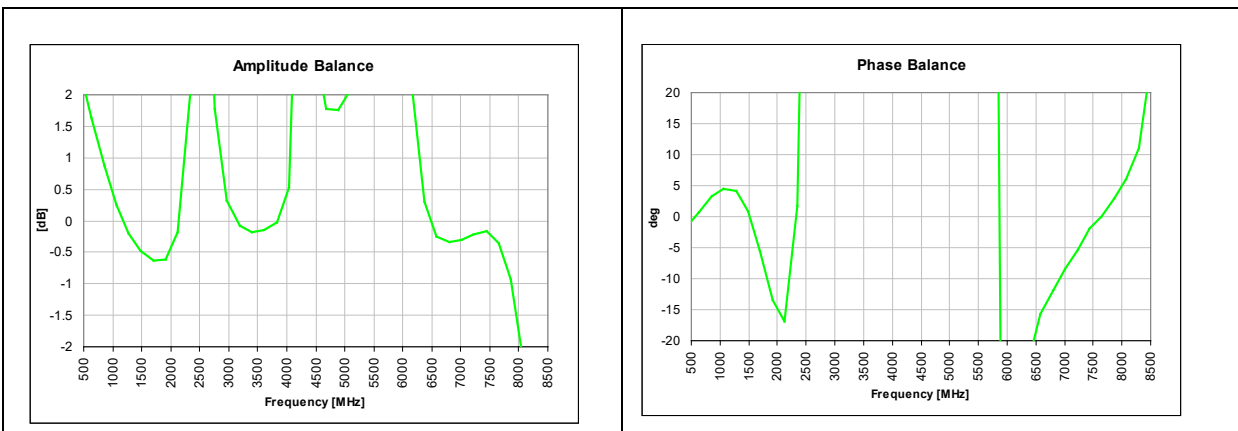
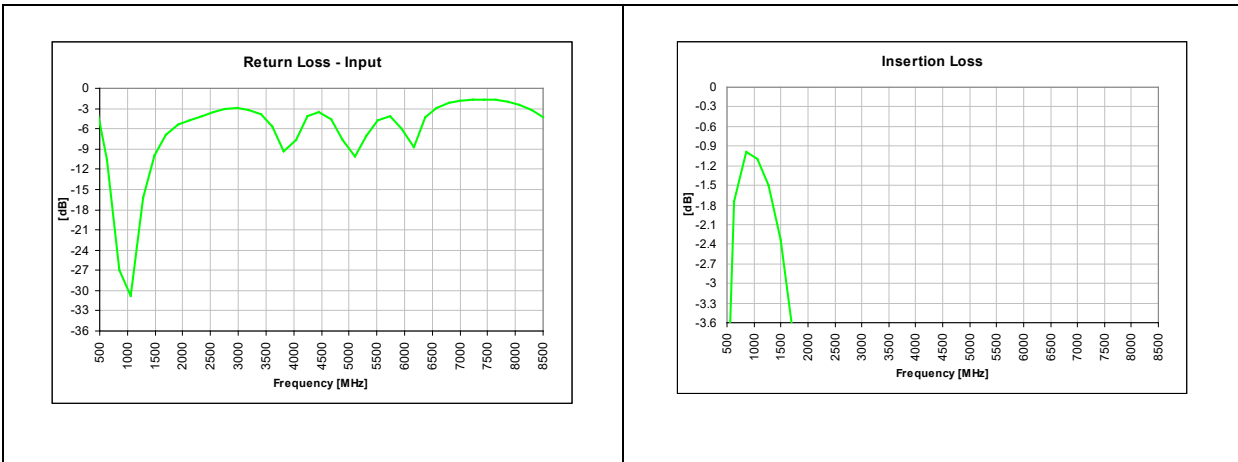


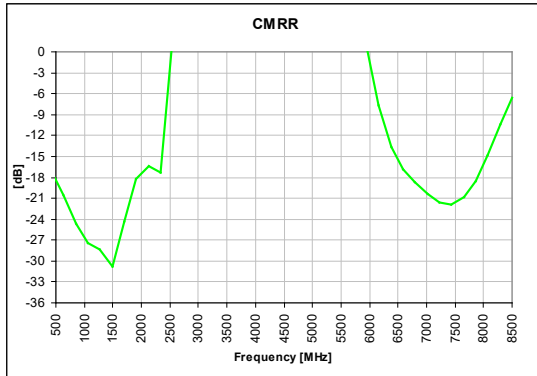
Typical Performance:





Wide Band Performance:





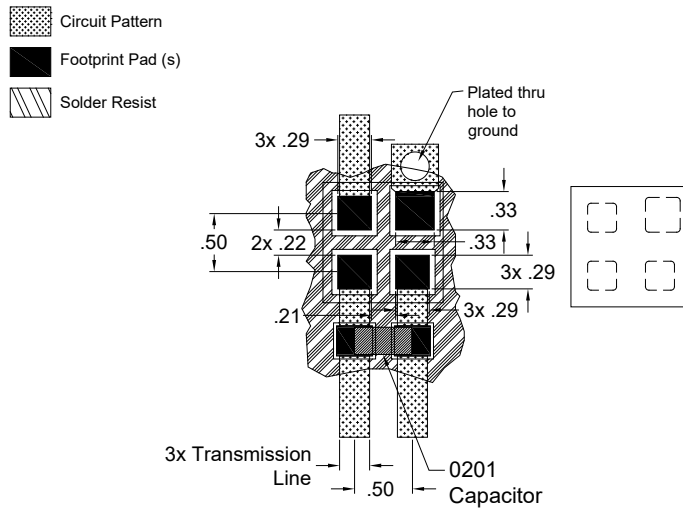
Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

An example of the PCB footprint used in the testing of these parts is shown below. **Note that the BD0810N50100AHF requires a 0201 size 1.6 pF capacitor across the differential (balanced) lines as shown in the diagram below for the specific case of a 5 mil thick Polyamide substrate.** This value may need to be adjusted slightly for different substrate thicknesses and dielectric constants.

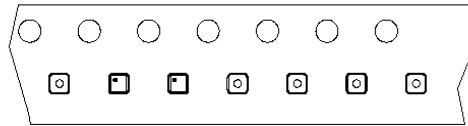
For specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.




Dimensions are in Millimeters
Mounting Footprint

Packaging and Ordering Information:

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel.



Direction of
Part Feed
(Unloading) 

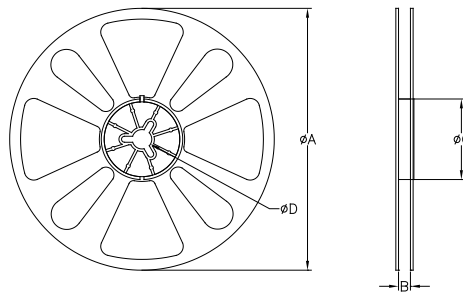


TABLE 1		
QUANTITY/REEL	REEL DIMENSIONS mm	
4000	ϕA	177.80
	B	8.00
	ϕC	50.80
	ϕD	13.00

Contact us:
rf&s_support@ttm.com